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- (54) Title:** A PROCESS FOR FORMING A LAMINATED STRUCTURE

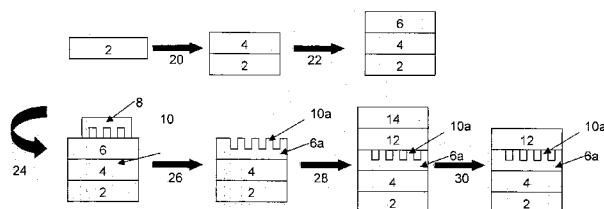


Fig. 1

- (57) Abstract:** There is provided a process for forming a laminated structure, the process comprising the step of bonding a polymer film to an array of structures disposed on a substrate, and wherein a plurality of cavities are formed between the polymer film and the array of structures during the bonding.